Teaching Bay Photoresist Spin Coat

Process Description:

For reproducible lithography, the photoresist needs to be uniform and pinhole-free. The standard method of application is spinning. In this method, the substrate is mounted on a vacuum chuck; a metered amount of photoresist is deposited onto the center of the wafer; and then the revolutions of wafer flings off the excess resist and a uniform film is produced. Viscosity of the photoresist, rotational speed and time of the spin are the controlling parameters.

Equipment Description:

The spin coat bench contains one Headway spinner with manual controller and hotplate. The spinner is capable of coating substrates up to 4 inches in diameter. A variety of chuck holders are available. The spin parameters are manually adjusted from 500 to 5,000 rpm and an electronic timer is manually set to automatically control the spin cycle.